

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) Encapsulation for an organic electronics component which is essentially manufactured from a molten mass of a metallic alloy.

2. (Original) Encapsulation according to claim 1, in which the alloy is present as a molten mass in a temperature range of 30 to 200°C.

3. (Currently amended) Encapsulation according to ~~one of~~ ~~claims~~ claim 1 or 2, in which the metallic alloy in a solidified form, provides a tight seal against moisture and/or oxidizing gases.

4. (Currently amended) Encapsulation according to ~~one of~~ ~~the preceding claims~~ claim 1, in which the alloy comprises at least one metal, selected from the following group of metals: Cadmium, tin, bismuth, lead, indium, mercury and/or silver.

5. (Currently amended) Encapsulation according to ~~one of~~ ~~the preceding claims~~ claim 1, in which the thickness of the encapsulation layer amounts to between 1 and 700µm.

6. (*Original*) Method for encapsulating an electronics component by applying the molten mass of a metallic alloy

7. (*Original*) Method according to claim 6, in which the molten mass is applied by means of a printing process.

8. (*Currently amended*) Method according to claim ~~6 or 7~~, in which the molten mass solidifies on the organic electronics component.

9. (*Currently amended*) Method according to ~~one of claims 6 to 8~~ claim 6, in which an insulating intermediate layer is applied to the organic electronics component prior to encapsulation.